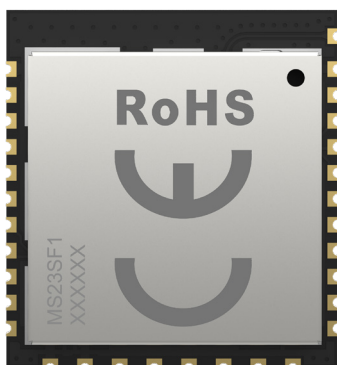


LoRaWAN Module

MS23SF1



Datasheet
V 1.0.0



MS23SF1-STM32WLE5CC

Low-power, ultra-long-range, small and easy to operate, high-sensitivity, support LoRaWAN

MS23SF1 Module is selected from ST LoRaWAN STM32WLE5CC, Wireless Half duplex transceiver chips, which supports global frequency ISM. It is a typical LoRa®WAN transceiver module, that supports multiple interfaces. The current in receive mode is only 4.2mA. It can achieve transmission power up to +20.5dBm with higher reception sensitivity, and down to -146dBm. compliance with the physical layer requirements of the LoRaWAN® standard specification, and support for LoRa® P2P(points-to-point).Supporting customers in the rapid set-up of their private, long-range LoRa® networks.

FEATURES



Small dimension, built-in 48MHz Arm Cortex-M4



Programmable bit rate, 64KB internal RAM, 256KB Flash



Transmission Range up to 5KM



Multi-IO port support GPIO24



Tx Power maximum up to +20.5dBm, RSSI -146dBm

KEY PARAMETER

MS23SF1

Chip Model	STM32WLE5CC	Antenna	None
Module size	20.72x19.13x3mm	GPIO	24
Flash	256KB	RAM	64KB
Receiving Sensitivity	-146dBm	Transmission Power	+20.5dBm
Current(TX)	120mA	Current(RX)	4.2mA

APPLICATION



Smart
Metering



Building
Automation



Agriculture
Sensor



Retail
Sensor

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RELATED DOCUMENTS

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